



AOS Thermal Compounds

U.S. Patent No. 6,475,962B1 & 6,900,163B2

MICRO-FAZE® A4

Dry Film Interface Material

Product Code: 52046

TECHNICAL DATA SHEET

THERMALLY CONDUCTIVE INTERFACE MATERIAL

Product Description

MICRO-FAZE® A4 is a revolutionary new thermal interface film formulated with **non-silicone thermal grease**. It was developed by AOS to offer the **lowest thermal resistance** in a thermal interface without the mess of grease. MICRO-FAZE A4 is a die-cut **aluminum foil substrate** coated on both sides with specially formulated thermal grease that is naturally tacky but dry to the touch. MICRO-FAZE A4 is non-wax-based and offers unique heat transfer properties.



Product Features & Benefits

- MICRO-FAZE A4 retains all the unique advantages of thermal grease but in the form of a thermal interface film.
- **Minimum force** is required to achieve total interface contact.
- MICRO-FAZE allows for **total “wetting action”** to fill all microscopic surface voids without changing phase.
- Unlike phase change materials, **heat transfer starts at 25°C** or lower, making MICRO-FAZE A4 an excellent choice for cold plate applications.
- Offers maximum heat transfer capability for power components.
- Excellent replacement for phase change materials and silicone pads.
- MICRO-FAZE A4 is a **“drop-in-place”** product that is easy to use and handle in a manufacturing environment.
- **Naturally tacky** – no adhesive, fiberglass or other non-conductive material is used that may penalize thermal resistance.
- Microscopically changes to fill all microscopic voids on part surfaces.
- **Thixotropic** nature prevents run out.

Major Applications

- Power modules, IGBTs, DC-DC converter modules, solid state relays, diodes, power MOSFETs, RF components and thermoelectric modules.
- Microprocessors, multichip modules, ASICs and other digital components.
- Power amplifiers, large area applications for power supplies and other custom enclosure heat dissipating surfaces.

Available Configurations

MICRO-FAZE A is available in rolls and can be die-cut to exact specifications.

Typical Properties

Physical Properties	A4
Substrate	Aluminum
Substrate Thickness	0.002in.
Compound Thickness (per side)	0.001in.
Total Thickness	0.004in.
Thermal Properties	
Thermal Resistance @ 50 psi	0.032 °C-in ² / W-mil
Thermal Conductivity (ASTM D-5470 modified)	4.5 W/m-K

AOS Thermal Compounds, 22 Meridian Road, Suite 6, Eatontown, NJ 07724
Tel 732.389.5514 Fax 732.389.6380 E-mail sales@aosco.com Web www.aosco.com